REMARKS

In the parent case, the Examiner rejected claims 3 and 4 under 35 USC 103(a) as unpatentable over US 4,344,006 to Mendelsohn or over EP0590975 to Tsai, in view of US 6,177,093 to Lombardi, and further in view of JP 359175751 A or JP 62005885 A. Applicant respectfully requests reconsideration in light of the following remarks.

The claims as now pending relate to method of marking a semiconductor die or wafer through use of a sprayable adhesive composition containing a colored filler.

Mendelsohn discloses a sprayable adhesive with an iron oxide pigment for making stator winding adhesive bracing compositions. The addition of the iron oxide is for the purpose of making the composition glossy. Moreover, the composition disclosed has a higher viscosity, as explained in the previous response in the parent case, than one that can be used for the method of instant claims 3 and 4 for use on a semiconductor. Tsai is directed to a sprayable epoxy adhesive, and Lombardi to using multiple colored pigments for cosmetics. There is no suggestion or motivation to combine these references, and even if they were combined, the combination would not yield applicant's invention of a method for marking semiconductors.

The Japanese abstracts disclose the laser marking of molded resins for the packaging of semiconductor devices. There is no suggestion or motivation to laser mark the silicon wafer or dies themselves. Thus, the combination of the Japanese abstracts and Mendelsohn or Tsai would not lead to the instant claims 3 and 4.

Applicant respectfully requests an allowance.

END OF REMARKS